Technical Data Sheet

Product Type: Non Conductive Adhesive
Product Name: NCA 5-107

ASSEMBLY MATERIALS

Description
NCA 5-107 is a fast curing thermosetting, high flexible, one-component, solvent-free non-conductive adhesive epoxy, designed for the connection of different components on lead frames, flex PCB material and foils.

Key Benefits
- High volume production possible
- High reliability
- Snap curing system

Compliant Products
- Conductive Adhesive: PC3200 and PC36000 Series
- Non-conductive Adhesive: NCA 6, NCA 11

Applications
- Dispensing

Physical Properties

<table>
<thead>
<tr>
<th>Pot Life (days)</th>
<th>Curing Profile</th>
<th>Substrate and Components</th>
</tr>
</thead>
<tbody>
<tr>
<td>5</td>
<td>1 min / 180 °C 2 min / 130 °C</td>
<td>Flex PCB, Lead frames and foils.</td>
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<tr>
<td></td>
<td></td>
<td>Recommended surface: Solder resist, Ni/Au and Ag</td>
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</tbody>
</table>

<table>
<thead>
<tr>
<th>Adhesion (N/mm²)</th>
<th>Weight Loss during Curing Process at 150 °C (%)</th>
<th>Glass Transition Temperature (°C)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Max. 26</td>
<td>Max. 0.1</td>
<td>Approx. 55</td>
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</tbody>
</table>

Cleaning Instructions
The uncured adhesive can be removed with Zestron HC and other Zestron and Vigon cleaning materials. The cleaned parts must be completely dry before installing them in the machine. Defective components can be removed by heating the cured adhesive joint with hot air above 250°C. The hot remaining adhesive can be removed with a sharp tool.

Adhesive Conditioning
- Remove adhesive from freezer: Before opening the package leave it for at least 2 hours at room temperature so that adhesive heats up
- Do not open jar/cartridge while adhesive is cold to prevent condensation
- Do not use faster defrost systems
Storage

- Store the adhesive in tightly-sealed containers and avoid exposure to high humidity and sunlight
- Store the cartridges with tip pointing downwards
- In cartridges: From the date of manufacture 12 months in a freezer at – 20 °C